

Type number	Package	Package description	Total product weight
74AUP1G06GN	SOT1115	X2SON6	0.86766 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935291715132	5	1	260	30 s	1	240	20 s	3	Bangkok, Thailand; Seremban, Malaysia; Nijmegen, Netherlands	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.03146	100.00000	3.62527
		subTotal		0.03146	100.00000	3.62527
Component	Additive	Non hazardous	Proprietary	0.00025	5.00000	0.02881
	Filler	Bisphenol-A/Epichlorohydrin Epoxy resin (generic)	25068-38-6	0.00025	5.00000	0.02881
		Silica -amorphous-	7631-86-9	0.00250	50.00000	0.28813
	Polymer	Epoxy resin system	Proprietary	0.00150	30.00000	0.17288
		Phenol Formaldehyde resin (generic)	9003-35-4	0.00050	10.00000	0.05763
		subTotal		0.00500	100.00000	0.57626
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	0.36386	94.51000	41.93618
		Magnesium (Mg)	7439-95-4	0.00058	0.15000	0.06656
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01136	2.95000	1.30898
		Silicon (Si)	7440-21-3	0.00246	0.64000	0.28398
	Pure metal layer	Gold (Au)	7440-57-5	0.00008	0.02000	0.00887
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.00631	1.64000	0.72770
		Palladium (Pd)	7440-05-3	0.00035	0.09000	0.03993
subTotal		0.38500	100.00000	44.37220		
Mould Compound	Additive	Misc. Phosphor compounds (generic)	7723-14-0	0.00044	0.10000	0.05013
		Non hazardous	Proprietary	0.01566	3.60000	1.80485
	Filler	Silica fused	60676-86-0	0.38280	88.00000	44.11866
	Pigment	Carbon black	1333-86-4	0.00087	0.20000	0.10027
		Phenolic resin	Proprietary	0.01784	4.10000	2.05553
	Polymer	Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.01740	4.00000	2.00539
subTotal			0.43500	100.00000	50.13483	
Wire	Gold alloy	Gold (Au)	7440-57-5	0.01110	99.00000	1.27906
		Palladium (Pd)	7440-05-3	0.00011	1.00000	0.01292
	subTotal		0.01121	100.00000	1.29198	

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, Nexperia does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. Nexperia may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.